AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions and listings of claims in the application:

Listing of Claims:

Claim 1 (Currently Amended): A method of fabricating a temperature control device [[(1)]] equipped with a temperature control element [[(2)]] configured by soft-soldering a thermionic element [[(9)]] between a pair of opposed electrodes ~~(7) and (8)~~ and a pair of heat conduction plates ~~(3) and (4)~~ disposed respectively on outside surfaces of respective insulating substrates ~~(5) and (6)~~ of the temperature control element [[(2)]] of ~~the relevant~~ a temperature control device,

said pairs of electrodes ~~(7) and (8)~~ are formed respectively on opposing surfaces of a pair of insulating substrates ~~(5) and (6)~~ disposed in opposed positions,

at least one plate [[(4)]] of said pair of heat conduction plates ~~(3) and (4)~~ is disposed on an outside surface of one of the insulating substrates [[(6)]] after soft soldering is performed with said thermionic element [[(9)]],

said one of the insulating substrates [[(6)]] on which said at least one plate [[(4)]] is disposed after soft soldering is flexible, and

in said soft soldering of thermionic element [[(9)]], a soft solder [[(12)]] in which a layer thickness control member is mixed ~~is used and is performed~~ while adding a predetermined pressure.

Claim 2 (Currently Amended): A method of fabricating a temperature control device [[(1)]] equipped with a temperature control element [[(2)]] configured by soft-soldering a thermionic element [[(9)]] between a pair of opposed electrodes ~~(7) and (8)~~ and a pair of heat conduction plates ~~(3) and (4)~~ disposed respectively on outside surfaces of respective insulating substrates ~~(5) and (6)~~ of ~~the relevant~~ a temperature control element [[(2)]],

the pair of electrodes ~~(7) and (8)~~ are formed respectively on opposing surfaces of a pair of insulating substrates ~~(5) and (6)~~ disposed in opposed positions,

at least one plate [[(4)]] of said pair of heat conduction plates ~~(3) and (4)~~ is disposed on an outside surface of one of the insulating substrates [[(6)]] after soft soldering is performed,

said one of the insulating substrates [[(6)]] on which said at least one plate [[(4)]] is disposed after soft soldering is flexible and

after soft soldering of said thermionic element [[(9)]] is performed, a soft solder layer [[(12a)]] is flattened by adding a pressure multiplied by 0.8 - 1.5 of yield stress at a temperature; ~~as well as~~ and said soft solder layer [[(12a)]] is heated to a first temperature which is the fusing point of a soft solder or to a temperature less than said first temperature and a second temperature which is the apparent initial softening point of a soft solder or to a temperature more than said second temperature.

Claim 3 (Currently Amended): The method of fabricating a temperature control device according to claim 2, wherein said soft solder layer [[(12a)]] contains a layer thickness control member.

Claim 4 (Currently Amended): A method of fabricating a temperature control device [[(1)]] equipped with a temperature control element [[(2)]] configured by soft-soldering a thermionic element [[(9)]] between a pair of opposed electrodes ~~(7) and (8)~~ and a pair of heat conduction plates ~~(3) and (4)~~ disposed respectively on outside surfaces of respective insulating substrates ~~(5) and (6)~~ of ~~the relevant~~ a temperature control element [[(2)]],

the pair of electrodes ~~(7) and (8)~~ are formed respectively on opposing surfaces of a pair of insulating substrates ~~(5) and (6)~~ disposed in opposed positions,

at least one plate [[(4)]] of said pair of heat conduction plates ~~(3) and (4)~~ is disposed on an outside surface of one of said pairs of insulating substrates [[(6)]] by making a grease layer ~~(10) stood between~~ provided therebetween,

the one of said pair of substrates [[(6)]] on which said at least one plate [[(4)]] is disposed, by ~~making~~ providing the grease layer ~~(10) stood between~~ therebetween, is flexible,

after said at least one plate [[(4)]] is disposed by ~~making~~ providing the grease layer ~~(10) stood~~ between the relevant plate [[(4)]] and one of said pair of insulating substrate [[(6)]], said grease layer [[(10)]] is flattened by adding a pressure in a range from 0.6 - 10 kg / cm^2 as well as heating in a range from 120-170 °C.

Claim 5 (Currently Amended): The method of fabricating a temperature control device according to claim 4, wherein after soft soldering of said thermionic element [[(9)]] is performed, [[said]] a soft solder layer [[(12a)]] is flattened by heating [[a]] said soft solder layer [[(12a)]] to a first temperature which is the fusing point of a soft solder or to a temperature less than said first temperature and a second temperature which is the apparent in itial softening point of a soft solder or to a temperature more than said second temperature;

adding a pressure multiplied by 0.8 - 1.5 of yield stress at a relevant temperature, and

flattening of said grease layer [[(10)]] and the flattening of said soft solder layer [[(12a)]] are carried out in the same time period.

Claim 6 (Currently Amended): The method of fabricating a temperature control device according to claim 5, wherein prior to soft soldering of said thermionic element [[(9)]], a heat conduction plate [[(4)]] is disposed by ~~making~~ providing the grease layer ~~(10) stood~~ between the relevant plate [[(4)]] and an insulating substrate [[(6)]].

Claim 7 (Currently Amended): The method of fabricating a temperature control device according to claim 5, wherein after soft soldering of said thermionic element [[(9)]] is performed, a heat conduction plate [[(4)]] is disposed by ~~making~~ providing the grease layer ~~(10) stood~~ between the relevant plate [[(4)]] and an insulating substrate [[(6)]].